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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	138
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-1fgg256

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

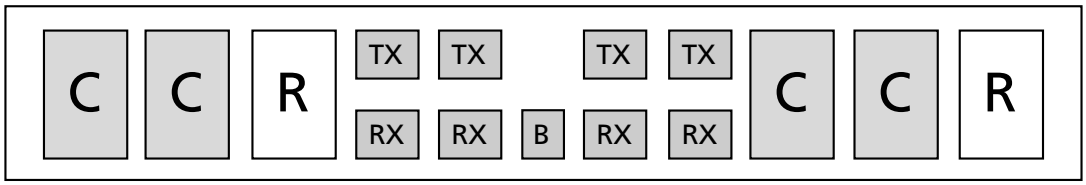


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

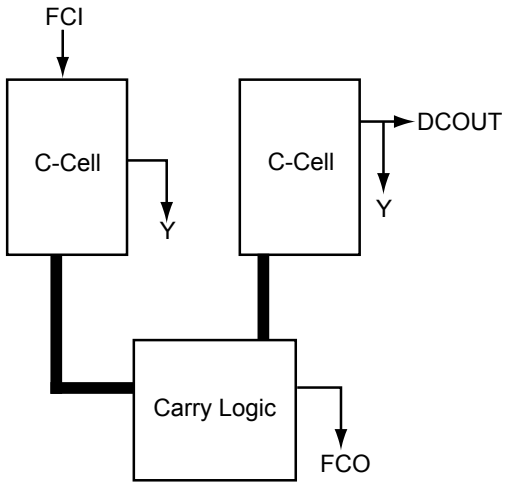


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

Using the Weak Pull-Up and Pull-Down Circuits

Each Axcelerator I/O comes with a weak pull-up/down circuit (on the order of 10 kΩ). These are weak transistors with the gates tied on, so the on resistance of the transistor emulates a resistor. The weak pull-up and pull-down is active only when the device is powered up, and they must be biased to be on. When the rails are coming up, they are not biased fully, so they do not behave as resistors until the voltage is at sufficient levels to bias the transistors. The key is they really are transistors; they are not traces of poly silicon, which is another way to do an on-chip resistor (those take much more room). I/O macros are provided for combinations of pull up/down for LVTTL, LVCMOS (2.5 V, 1.8 V, and 1.5 V) standards. These macros can be instantiated if a keeper circuit for any input buffer is required.

Customizing the I/O

- A five-bit programmable input delay element is associated with each I/O. The value of this delay is set on a bank-wide basis (Table 2-14). It is optional for each input buffer within the bank (i.e. the user can enable or disable the delay element for the I/O). When the input buffer drives a register within the I/O, the delay element is activated by default to ensure a zero hold-time. The default setting for this property can be set in Designer. When the input buffer does not drive a register, the delay element is deactivated to provide higher performance. Again, this can be overridden by changing the default setting for this property in Designer.
- The slew-rate value for the LVTTL output buffer can be programmed and can be set to either slow or fast.
- The drive strength value for LVTTL output buffers can be programmed as well. There are four different drive strength values – 8 mA, 12 mA, 16 mA, or 24 mA – that can be specified in Designer.[5]

Table 2-14 • **Bank-Wide Delay Values**

Bits Setting	Delay (ns)	Bits Setting	Delay (ns)
0	0.54	16	2.01
1	0.65	17	2.13
2	0.71	18	2.19
3	0.83	19	2.3
4	0.9	20	2.38
5	1.01	21	2.49
6	1.08	22	2.55
7	1.19	23	2.67
8	1.27	24	2.75
9	1.39	25	2.87
10	1.45	26	2.93
11	1.56	27	3.04
12	1.64	28	3.12
13	1.75	29	3.23
14	1.81	30	3.29
15	1.93	31	3.41

Note: Delay values are approximate and will vary with process, temperature, and voltage.

5. *These values are minimum drive strengths.*

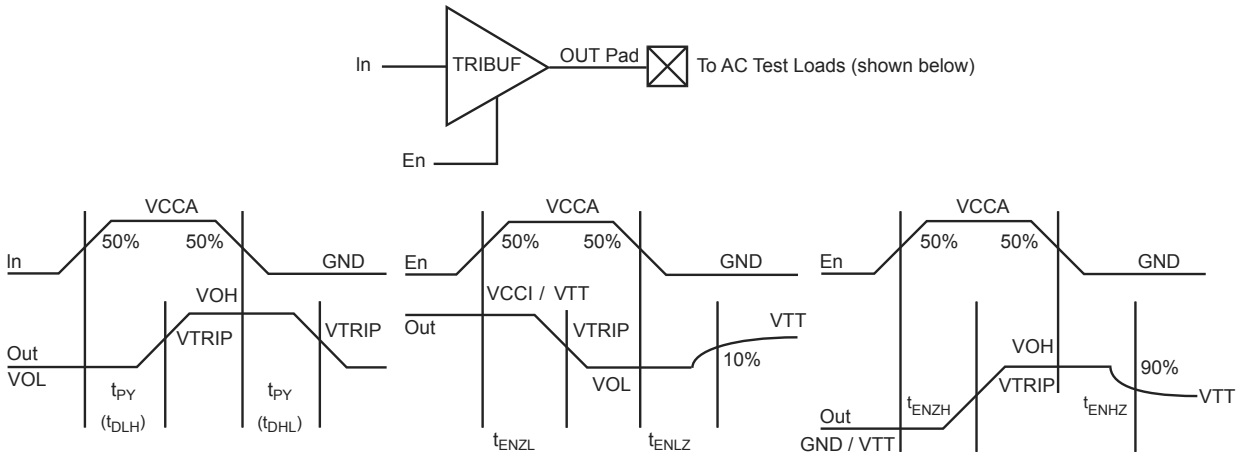


Figure 2-10 • **Output Buffer Delays**

3.3 V LVTTL

Low-Voltage Transistor-Transistor Logic is a general purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer.

***Table 2-20* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.8	2.0	3.6	0.4	2.4	24	–24

AC Loadings

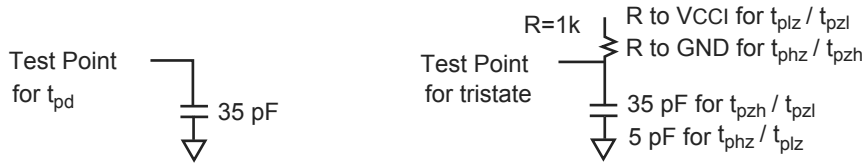


***Figure 2-15 •* AC Test Loads**

***Table 2-21* • AC Waveforms, Measuring Points, and Capacitive Load**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	3.0	1.40	N/A	35

*Note: * Measuring Point = VTRIP*

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 2 (12 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		3.30		3.76		4.42	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.74		4.26		5.00	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.06		3.49		4.10	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.89		1.91		1.91	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.29		2.30		2.31	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Model and Waveforms

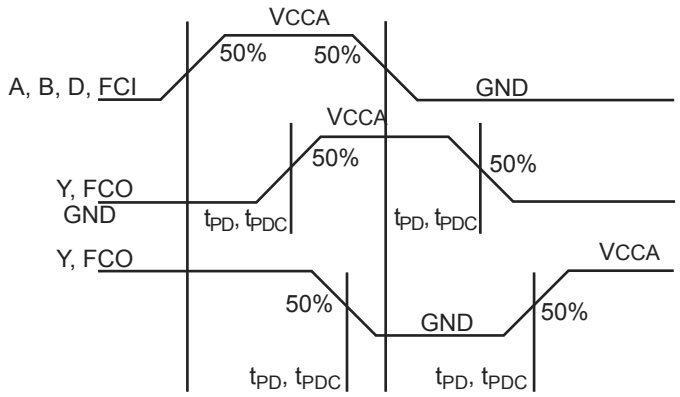


Figure 2-28 • **C-Cell Timing Model and Waveforms**

Timing Characteristics

Table 2-62 • **C-Cell**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
C-Cell Propagation Delays								
t_{PD}	Any input to output Y		0.74		0.84		0.99	ns
t_{PDC}	Any input to carry chain output (FCO)		0.57		0.64		0.76	ns
t_{PDB}	Any input through DB when one input is used		0.95		1.09		1.28	ns
t_{CCY}	Input to carry chain (FCI) to Y		0.61		0.69		0.82	ns
t_{CC}	Input to carry chain (FCI) to carry chain output (FCO)		0.08		0.09		0.11	ns

R-Cell

Introduction

The R-cell, the sequential logic resource of the Axcelerator devices, is the second logic module type in the AX family architecture. It includes clock inputs for all eight global resources of the Axcelerator architecture as well as global presets and clears (Figure 2-31).

The main features of the R-cell include the following:

- Direct connection to the adjacent logic module through the hardwired connection DCIN. DCIN is driven by the DCOUT of an adjacent C-cell via the Direct-Connect routing resource, providing a connection with less than 0.1 ns of routing delay.
- The R-cell can be used as a standalone flip-flop. It can be driven by any C-cell or I/O modules through the regular routing structure (using DIN as a routable data input). This gives the option of using the R-Cell as a 2:1 MUXed flip-flop as well.
- Provision of data enable-input (S0).
- Independent active-low asynchronous clear (CLR).
- Independent active-low asynchronous preset (PSET). If both CLR and PSET are low, CLR has higher priority.
- Clock can be driven by any of the following (CKP selects clock polarity):
  - One of the four high performance hardwired fast clocks (HCLKs)
  - One of the four routed clocks (CLKs)
  - User signals
- Global power-on clear (GCLR) and preset (GPSET), which drive each flip-flop on a chip-wide basis.
  - When the Global Set Fuse option in the Designer software is unchecked (by default), GCLR = 0 and GPSET = 1 at device power-up. When the option is checked, GCLR = 1 and GPSET = 0. Both pins are pulled High when the device is in user mode. Refer to the "Simulation Support for GCLR/GPSET in Axcelerator" section of the *Antifuse Macro Library Guide* for information on simulation support for GCLR and GPSET.
- S0, S1, PSET, and CLR can be driven by routed clocks CLKE/F/G/H or user signals.
- DIN and S1 can be driven by user signals.

As with the C-cell, the configuration of the R-cell to perform various functions is handled automatically for the user through Microsemi's extensive macro library (see the *Antifuse Macro Library Guide* for a complete listing of available AX macros).

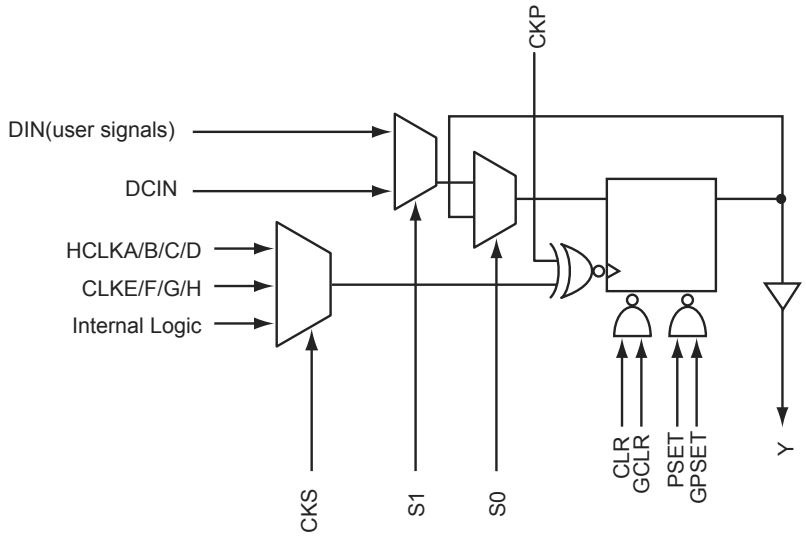


Figure 2-31 • **R-Cell**

***Table 2-67* • AX500 Predicted Routing Delays**
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.39	0.45	0.53	ns
t_{RD2}	Routing delay for FO2	0.41	0.46	0.54	ns
t_{RD3}	Routing delay for FO3	0.48	0.55	0.64	ns
t_{RD4}	Routing delay for FO4	0.56	0.63	0.75	ns
t_{RD5}	Routing delay for FO5	0.60	0.68	0.80	ns
t_{RD6}	Routing delay for FO6	0.84	0.96	1.13	ns
t_{RD7}	Routing delay for FO7	0.90	1.02	1.20	ns
t_{RD8}	Routing delay for FO8	1.00	1.13	1.33	ns
t_{RD16}	Routing delay for FO16	2.17	2.46	2.89	ns
t_{RD32}	Routing delay for FO32	3.55	4.03	4.74	ns

***Table 2-68* • AX1000 Predicted Routing Delays**
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.12	0.13	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.45	0.51	0.60	ns
t_{RD2}	Routing delay for FO2	0.53	0.60	0.71	ns
t_{RD3}	Routing delay for FO3	0.56	0.63	0.74	ns
t_{RD4}	Routing delay for FO4	0.63	0.71	0.84	ns
t_{RD5}	Routing delay for FO5	0.73	0.82	0.97	ns
t_{RD6}	Routing delay for FO6	0.99	1.13	1.32	ns
t_{RD7}	Routing delay for FO7	1.02	1.15	1.36	ns
t_{RD8}	Routing delay for FO8	1.48	1.68	1.97	ns
t_{RD16}	Routing delay for FO16	2.57	2.91	3.42	ns
t_{RD32}	Routing delay for FO32	4.24	4.81	5.65	ns

Routed Clocks

The routed clock (CLK) is a low-skew network that can drive the clock inputs of all sequential modules in the device (logically equivalent to the HCLK), but has the added flexibility in that it can drive the S0 (Enable), S1, PSET, and CLR input of a register (R-cells and I/O registers) as well as any of the inputs of any C-cell in the device. This allows CLKs to be used not only as clocks, but also for other global signals or high fanout nets. All four CLKs are available everywhere on the chip.

Timing Characteristics

Table 2-75 • **AX125 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t_{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

Table 2-76 • **AX250 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		2.52		2.87		3.37	ns
t_{RCKH}	Input High to Low		2.59		2.95		3.47	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

Axcelerator Clock Management System

Introduction

Each member of the Axcelerator family[6] contains eight phase-locked loop (PLL) blocks which perform the following functions:

- Programmable Delay (32 steps of 250 ps)
- Clock Skew Minimization
- Clock Frequency Synthesis

Each PLL has the following key features:

- Input Frequency Range – 14 to 200 MHz
- Output Frequency Range – 20 MHz to 1 GHz
- Output Duty Cycle Range – 45% to 55%
- Maximum Long-Term Jitter – 1% or 100ps (whichever is greater)
- Maximum Short-Term Jitter – 50ps + 1% of Output Frequency
- Maximum Acquisition Time (lock) – 20µs

Physical Implementation

The eight PLL blocks are arranged in two groups of four. One group is located in the center of the northern edge of the chip, while the second group is centered on the southern edge. The northern group is associated with the four HCLK networks (e.g. PLLA can drive HCLKA), while the southern group is associated with the four CLK networks (e.g. PLLE can drive CLKE).

Each PLL cell is connected to two I/O pads and a PLL Cluster that interfaces with the FPGA core. Figure 2-48 illustrates a PLL block. The VCCPLL pin should be connected to a 1.5V power supply through a 250 Ω resistor. Furthermore, 0.1 µF and 10 µF decoupling capacitors should be connected across the VCCPLL and VCOMPPLL pins.

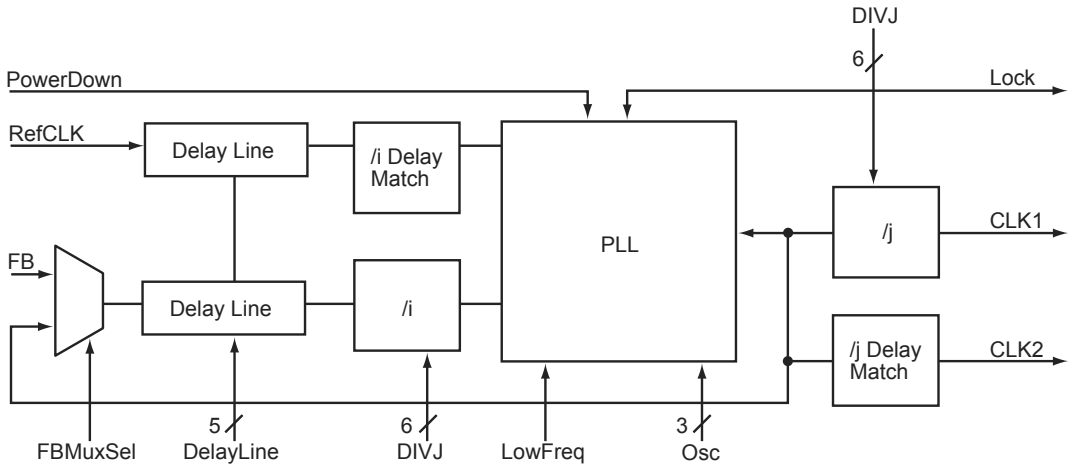


Figure 2-48 • **PLL Block Diagram**

Note: The VCOMPPLL pin should never be grounded (Figure 2-2 on page 2-9)!

The I/O pads associated with the PLL can also be configured for regular I/O functions except when it is used as a clock buffer. The I/O pads can be configured in all the modes available to the regular I/O pads in the same I/O bank. In particular, the [H]CLKxP pad can be configured as a differential pair,

6. *AX2000-CQ256 does not support operation of the phase-locked loops. This is in order to support full pin compatibility with RTAX2000S/SL-CQ256.*

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

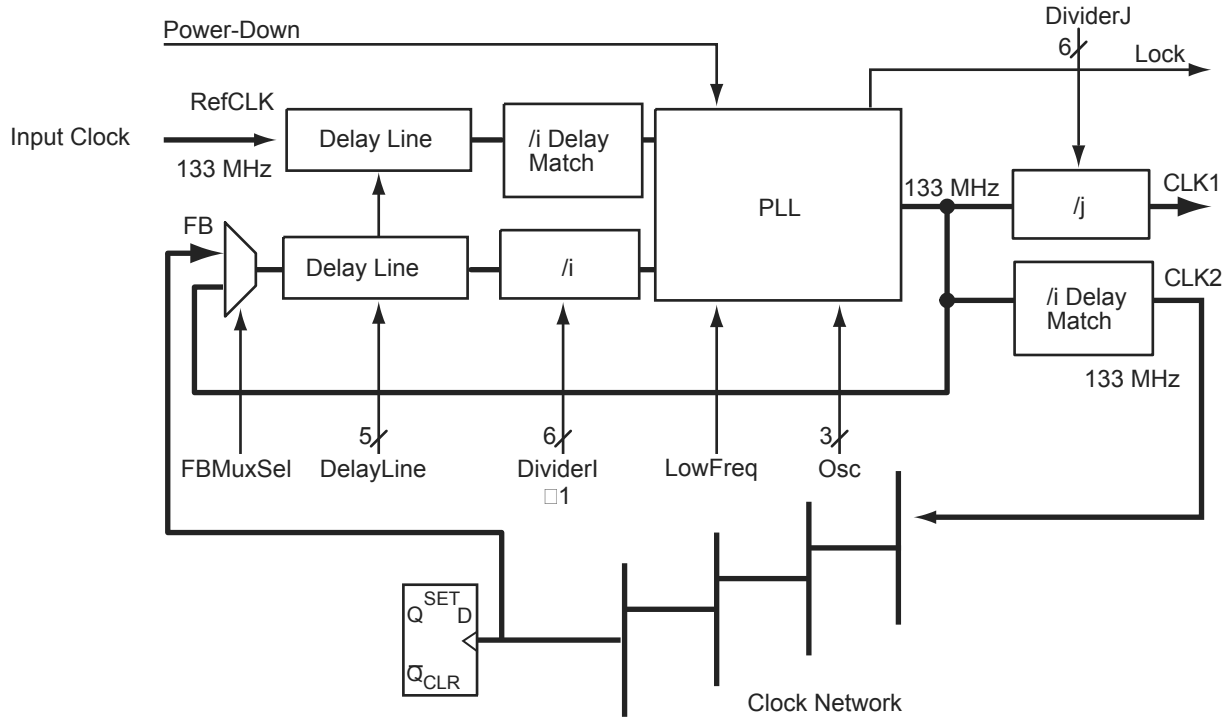
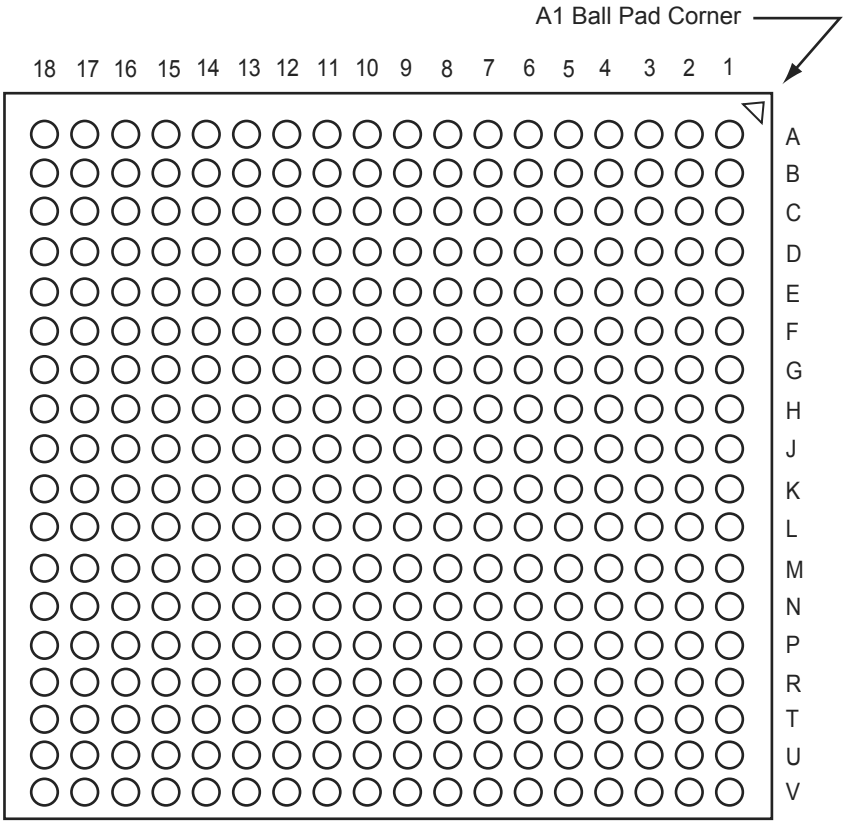


Figure 2-56 • **Using the PLL for Clock Deskewing**

FG324



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG676	
AX500 Function	Pin Number
Bank 0	
IO00NB0F0	F8
IO00PB0F0	E8
IO01NB0F0	A5
IO01PB0F0	A4
IO02NB0F0	E7
IO02PB0F0	E6
IO03NB0F0	D6
IO03PB0F0	D5
IO04NB0F0	B5
IO04PB0F0	C5
IO05NB0F0	B6
IO05PB0F0	C6
IO06NB0F0	C7
IO06PB0F0	D7
IO07NB0F0	A7
IO07PB0F0	A6
IO08NB0F0	C8
IO08PB0F0	D8
IO09NB0F0	F10
IO09PB0F0	F9
IO10NB0F0	B8
IO10PB0F0	B7
IO11NB0F0	D10
IO11PB0F0	E10
IO12NB0F1	B9
IO12PB0F1	C9
IO13NB0F1	F11
IO13PB0F1	G11
IO14NB0F1	D11
IO14PB0F1	E11
IO15NB0F1	B10
IO15PB0F1	C10
IO16NB0F1	A10
IO16PB0F1	A9

FG676	
AX500 Function	Pin Number
IO17NB0F1	F12
IO17PB0F1	G12
IO18NB0F1	C12
IO18PB0F1	C11
IO19NB0F1/HCLKAN	A12
IO19PB0F1/HCLKAP	B12
IO20NB0F1/HCLKBN	C13
IO20PB0F1/HCLKBP	B13
Bank 1	
IO21NB1F2/HCLKCN	C15
IO21PB1F2/HCLKCP	C14
IO22NB1F2/HCLKDN	A15
IO22PB1F2/HCLKDP	B15
IO23NB1F2	F15
IO23PB1F2	G15
IO24NB1F2	B16
IO24PB1F2	A16
IO25NB1F2	A18
IO25PB1F2	A17
IO26NB1F2	D16
IO26PB1F2	E16
IO27NB1F2	F16
IO27PB1F2	G16
IO28NB1F2	C18
IO28PB1F2	C17
IO29NB1F2	B19
IO29PB1F2	B18
IO30NB1F2	D19
IO30PB1F2	C19
IO31NB1F2	F17
IO31PB1F2	E17
IO32NB1F3	B20
IO32PB1F3	A20
IO33NB1F3	B22
IO33PB1F3	B21

FG676	
AX500 Function	Pin Number
IO34NB1F3	D20
IO34PB1F3	C20
IO35NB1F3	D21
IO35PB1F3	C21
IO36NB1F3	D22
IO36PB1F3	C22
IO37NB1F3	F19
IO37PB1F3	E19
IO38NB1F3	B23
IO38PB1F3	A23
IO39NB1F3	E21
IO39PB1F3	E20
IO40NB1F3	D23
IO40PB1F3	C23
IO41NB1F3	D25
IO41PB1F3	C25
Bank 2	
IO42NB2F4	G24
IO42PB2F4	G23
IO43NB2F4	G26
IO43PB2F4	F26
IO44NB2F4	F25
IO44PB2F4	E25
IO45NB2F4	J21
IO45PB2F4	J22
IO46NB2F4	H25
IO46PB2F4	G25
IO47NB2F4	K23
IO47PB2F4	J23
IO48NB2F4	J24
IO48PB2F4	H24
IO49NB2F4	K21
IO49PB2F4	K22
IO50NB2F4	K25
IO50PB2F4	J25

FG676	
AX1000 Function	**Pin Number**
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	**Pin Number**
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	**Pin Number**
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896	
AX2000 Function	Pin Number
GND	AK18
GND	AK2
GND	AK23
GND	AK29
GND	AK8
GND	B1
GND	B2
GND	B22
GND	B29
GND	B30
GND	B9
GND	C10
GND	C15
GND	C16
GND	C21
GND	C28
GND	C3
GND	D27
GND	D28
GND	D4
GND	E26
GND	E5
GND	H1
GND	H30
GND	J2
GND	J22
GND	J29
GND	J9
GND	K10
GND	K21
GND	K28
GND	K3
GND	L11
GND	L20
GND	M12

FG896	
AX2000 Function	Pin Number
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	M18
GND	M19
GND	N1
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N18
GND	N19
GND	N30
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R28
GND	R3

FG896	
AX2000 Function	Pin Number
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T28
GND	T3
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18
GND	U19
GND	V1
GND	V12
GND	V13
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V30
GND	W12
GND	W13
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

CQ208	
AX500 Function	Pin Number
IO150PB7F14	19
IO152NB7F14	16
IO152PB7F14	17
IO161NB7F15	12
IO161PB7F15	13
IO163NB7F15	10
IO163PB7F15	11
IO165PB7F15	7
IO166NB7F15	5
IO166PB7F15	6
IO167NB7F15	3
IO167PB7F15	4
Dedicated I/O	
VCCDA	1
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169

CQ208	
AX500 Function	Pin Number
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193

CQ208	
AX500 Function	Pin Number
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

Revision	Changes	Page
Revision 17 (continued)	The C180 package was removed from product tables and the "Package Pin Assignments" section (PDN 0909).	3-1
	Package names used in the"Axcelerator Family Product Profile" and "Package Pin Assignments" section were revised to match standards given in *Package Mechanical Drawings* (SAR 27395).	i, 3-1
	The "Introduction" section for "User I/Os" was updated as follows: "The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os" (SARs 24181, 24309).	2-11
	Power values in Table 2-4 • Default CLOAD/VCCI were updated to reflect those of SmartPower (SAR 33945).	2-3
	Two parameter names were corrected in Figure 2-10 • Output Buffer Delays. One occurrence of t_{ENLZ} was changed to t_{ENZL} and one occurrence of t_{ENHZ} was changed to t_{ENZH} (SAR 33890).	2-22
	The "Timing Model" section was updated with new timing values. Timing tables in the "I/O Specifications" section were updated to include enable paths. Values in the timing tables in the "Voltage-Referenced I/O Standards" section and "Differential Standards" section were updated. Table 2-63 • R-Cell was updated (SAR 33945).	2-8, 2-26 to 2-53
	Figure 2-11 • Timing Model was replaced (SAR 33043).	2-23
	The timing tables for "RAM" and "FIFO" were updated (SAR 33945).	2-90 to 2-106
	"Data Registers (DRs)" values were modified for IDCODE and USERCODE (SARs 18257, 26406).	2-108
	The package diagram for the "CQ208" package was incorrect and has been replaced with the correct diagram (SARs 23865, 26345).	3-89
Revision 16 (v2.8, Oct. 2009)	The datasheet was updated to include AX2000-CQ2526 information.	N/A
	MIL-STD-883 Class B is no longer supported by Axcelerator FPGAs and as a result was removed.	N/A
	A footnote was added to the "Introduction" in the "Axcelerator Clock Management System" section.	2-75
Revision 15 (v2.7, Nov. 2008)	RoHS-compliant information was added to the "Ordering Information".	ii
	ACTgen was changed to SmartGen because ACTgen is obsolete.	N/A
Revision 14 (v2.6)	In Table 2-4, the units for the P_{LOAD}, P_{10}, and $P_{I/O}$ were updated from mW/MHz to mW/MHz.	2-3
	In the "Pin Descriptions"section, the HCLK and CLK descriptions were updated to include tie-off information.	2-9
	The "Global Resource Distribution" section was updated.	2-70
	The " CG624" table was updated.	3-116
Revision 13 (v2.5)	A note was added to Table 2-2.	2-1
	In the "Package Thermal Characteristics", the temperature was changed from 150°C to 125°C.	2-6

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "Axcelerator Family Device Status" table on page iii, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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